HOSTAFORM® C 13031 10/9022

HOSTAFORM®

Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GNR, 04-002 POM copolymer Easy flowing Injection molding type like C 13021, but with higher strength, rigidity and hardness over the entire permissible temperature range for HOSTAFORM; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. Hostaform® C 13031 10/9022 has been specially formulated for laser welding applications. Ranges of applications: For molded parts with higher requirements to strength, rigidity und hardness.

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	12	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	

Typical mechanical properties

Tensile modulus	3100	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	70	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	8	%	ISO 527-1/-2
Nominal strain at break	20	%	ISO 527-1/-2
Flexural modulus	3000	MPa	ISO 178
Tensile creep modulus, 1h	2750	MPa	ISO 899-1
Tensile creep modulus, 1000h	1450	MPa	ISO 899-1
Charpy impact strength, 23°C	120	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	120	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	6	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	6	kJ/m^2	ISO 179/1eA
Ball indentation hardness, H 358/30	156	MPa	ISO 2039-1
Poisson's ratio	0.37[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	170	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	112	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	120	E-6/K	ISO 11359-1/-2

Electrical properties

Relative permittivity, 100Hz	4		IEC 62631-2-1
Relative permittivity, 1MHz	4		IEC 62631-2-1
Dissipation factor, 100Hz	20	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50	E-4	IEC 62631-2-1
Electric strength	35	kV/mm	IEC 60243-1

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Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	1410	kg/m^3	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa

Characteristics

Processing	Injection Moulding

Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Melt temperature 190-210 °C
Mould temperature 80-120 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

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